LNJ837W86RA

Hight Bright Surface Mounting Chip LED

ESS II Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	55	mW	
Forward current	I_{F}	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

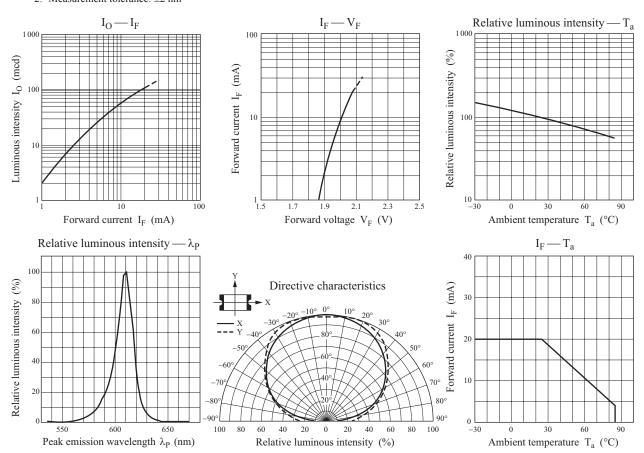
• Soft Orange

■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	I _O	$I_F = 5 \text{ mA}$	11.5	27.5	60.5	mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	$V_{\rm F}$	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	λ_{P}	$I_F = 5 \text{ mA}$		610		nm
Dominant emission wavelength *2	λ_{d}	$I_F = 5 \text{ mA}$	597	605	615	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		15		nm

Note) *1: Measurement tolerance: ±20%

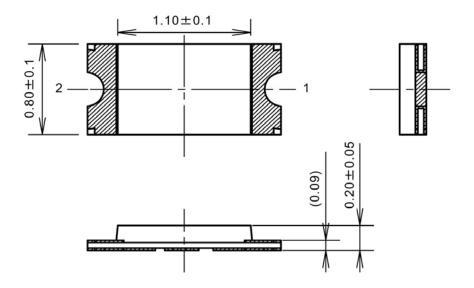
^{*2:} Measurement tolerance: ±2 nm

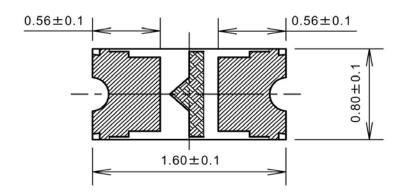


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■ Package (Unit: mm)

KLTFTN2K3700





- Pin name
 - 1: Anode
 - 2: Cathode

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